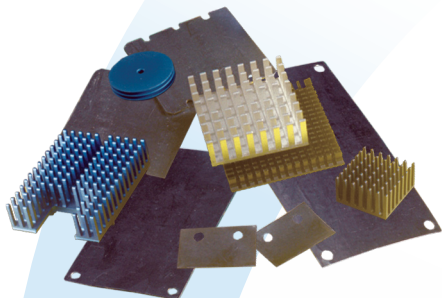


Tgon™ 800 Series

Electrically and Thermally Conductive Interface Pad



HIGH-PERFORMANCE, COST EFFECTIVE THERMAL INTERFACE MATERIAL

Used where electrical isolation is not required, Tgon™ 800 is ideal for where electrical contact and thermal transfer are desired.

Its unique grain-oriented, plate-like structure provides a high thermal conductivity of 240 W/mK in the XY plane and 5 W/mK through the z-axis.. Tgon 800 can be supplied in 12" x 18" (305mm x 457mm) or 18" x 24" (457mm x 610mm) sheets, rolls or die-cut to specific configurations.

It is also available with proprietary pressure sensitive adhesive on one side. This adhesive coating is the thinnest available, minimizing any impact on thermal performance.

FEATURES

- High thermal conductivity of 5 W/mK in Z axis and 240 W/mK in the X-Y axis
- >98% graphite
- Low thermal resistance
- Thicknesses of 0.005", 0.010" and 0.020" (0.125mm, 0.25mm, and 0.50mm)

APPLICATIONS

- Power conversion equipment
- Power supplies
- Large telecommunications switching hardware
- Notebook computers
- Where electrical grounding is required with good thermal conductivity

global solutions: local support™

Americas: +1.888.246.9050

Europe: +49.0.8031.2460.0

Asia: +86.755.2714.1166

CLV-customerservice@lairdtech.com

www.lairdtech.com/thermal

Tgon™ 800 Series

Electrically and Thermally Conductive Interface Pad

TGON™ 800 TYPICAL PROPERTIES

	TGON™ 805	TGON™ 810	TGON™ 820	TEST METHOD
Construction & Composition	Flexible Graphite	Flexible Graphite	Flexible Graphite	
Color	Pewter	Pewter	Pewter	Visual
Thickness	0.005" (0.13mm)	0.010" (0.25mm)	0.020" (0.51mm)	
Thickness Tolerance	± 0.001" (± 0.025mm)	± 0.001" (± 0.025mm)	± 0.002" (± 0.05mm)	
Density	2.20 g/cc	2.20 g/cc	2.20 g/cc	Helium Pycnometer
Hardness	85 Shore A	85 Shore A	85 Shore A	ASTM D2240
Tensile strength	650 psi	650 psi	650 psi	ASTM D412
Outgassing TML	0.15%	0.15%	0.15%	ASTM E595
Outgassing CVCm	0.09%	0.09%	0.09%	ASTM E595
UL Flammability rating	94 VO	94 VO	94 VO	
Temperature range	-240°C to 300°C	-240°C to 300°C	-240°C to 300°C	
Thermal conductivity - Z Axis	5 W/mK	5 W/mK	5 W/mK	ASTM D5470 (modified)
Thermal conductivity - XY Axis	240 W/mK	240 W/mK	240 W/mK	ASTM D5470 (modified)
Thermal resistance @ 100 psi	0.07 °C-in²/W	0.10 °C-in²/W	0.17 °C-in²/W	ASTM D5470 (modified)
Thermal resistance @ 681 KPa	0.42 °C-cm²/W	0.66 °C-cm²/W	1.07 °C-cm²/W	ASTM D5470 (modified)
Volume resistivity (In-Plane)	11 x 10 ⁻⁵ ohm-cm	11 x 10 ⁻⁵ ohm-cm	11 x 10 ⁻⁵ ohm-cm	ASTM D257

STANDARD THICKNESSES

0.005" (0.13mm), 0.010" (0.25mm), 0.020" (0.51mm)

Consult the factory for alternate thicknesses.

STANDARD SHEET SIZE

18" x 24" (457mm x 609.6mm)

Tgon™ 800 sheets are supplied with no liners when ordered without adhesive.

With adhesive, they are supplied with no top liner and white release liner on the bottom.

Tgon™ 800 is available on rolls and individual die cut shapes.

PRESSURE SENSITIVE ADHESIVE

Request no adhesive with "AO" suffix.

Request adhesive on one side with "A1" suffix.

Striped adhesive option on one side designated with SA.

Double-sided adhesive is not available.

THR-DS-Tgon-800 1109

Any information furnished by Laird Technologies, Inc. and its agents is believed to be accurate and reliable. All specifications are subject to change without notice. Responsibility for the use and application of Laird Technologies materials rests with the end user, since Laird Technologies and its agents cannot be aware of all potential uses. Laird Technologies makes no warranties as to the fitness, merchantability or suitability of any Laird Technologies materials or products for any specific or general uses. Laird Technologies shall not be liable for incidental or consequential damages of any kind. All Laird Technologies products are sold pursuant to the Laird Technologies' Terms and Conditions of sale in effect from time to time, a copy of which will be furnished upon request. © Copyright 2009 Laird Technologies, Inc. All Rights Reserved. Laird, Laird Technologies, the Laird Technologies Logo, and other marks are trade marks or registered trade marks of Laird Technologies, Inc. or an affiliate company thereof. Other product or service names may be the property of third parties. Nothing herein provides a license under any Laird Technologies or any third party intellectual property rights. A13515-00 Rev I 11/2009